



DO214AC (SMA) Rectifier

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Frame 35.89%	Copper (Cu)	7440-50-8	23.80230	99.9787	359077.4
	Phosphorus (P)	7723-14-0	0.00024	0.0010	3.6
	Arsenic (As)	7440-38-2	0.00024	0.0010	3.6
	Tin (Sn)	7440-31-5	0.00024	0.0010	3.6
	Oxygen (O)	7782-44-7	0.00012	0.0005	1.8
	Sulfur (S)	7704-34-9	0.00286	0.0120	43.2
	Iron (Fe)	7439-89-6	0.00016	0.0007	2.4
	Nickel (Ni)	7440-02-0	0.00007	0.0003	1.1
	Bismuth (Bi)	7440-69-9	0.00048	0.0020	7.2
	Antimony (Sb)	1309-64-4	0.00048	0.0020	7.2
	Lead (Pb)	7439-92-1	0.00012	0.0005	1.8
	Zinc (Zn)	7440-66-6	0.00007	0.0003	1.1
		Total		23.81	
Solder Wafer 1.17%	Lead (Pb)	7439-92-1	0.72	92.50	10,884.4
	Tin (Sn)	7440-31-5	0.04	5.00	588.3
	Silver (Ag)	7440-22-4	0.02	2.50	294.2
		Total		0.78	
Chip 1.34%	Silicon (Si)	7440-21-3	0.84	100.00	12,672.1
		Total		0.84	
Molding 60.81%	Silica (SiO ₂)	14808-60-7	29.896	74.11	451,005.6
	Epoxy resin	29690-82-2	6.858	17.00	103,455.6
	Phenolic resin	9003-35-4	3.550	8.80	53,553.5
	Phosphorus(P)	7723-14-0	0.020	0.05	304.3
	Carbon Black	1333-86-4	0.016	0.04	243.4
		Total		40.34	
Plating 0.79%	Tin (Sn)	7440-31-5	0.52	100.00	7,844.6
		Total		0.52	
	Total mass (mg)		66.29		

